







OFFER 6994160

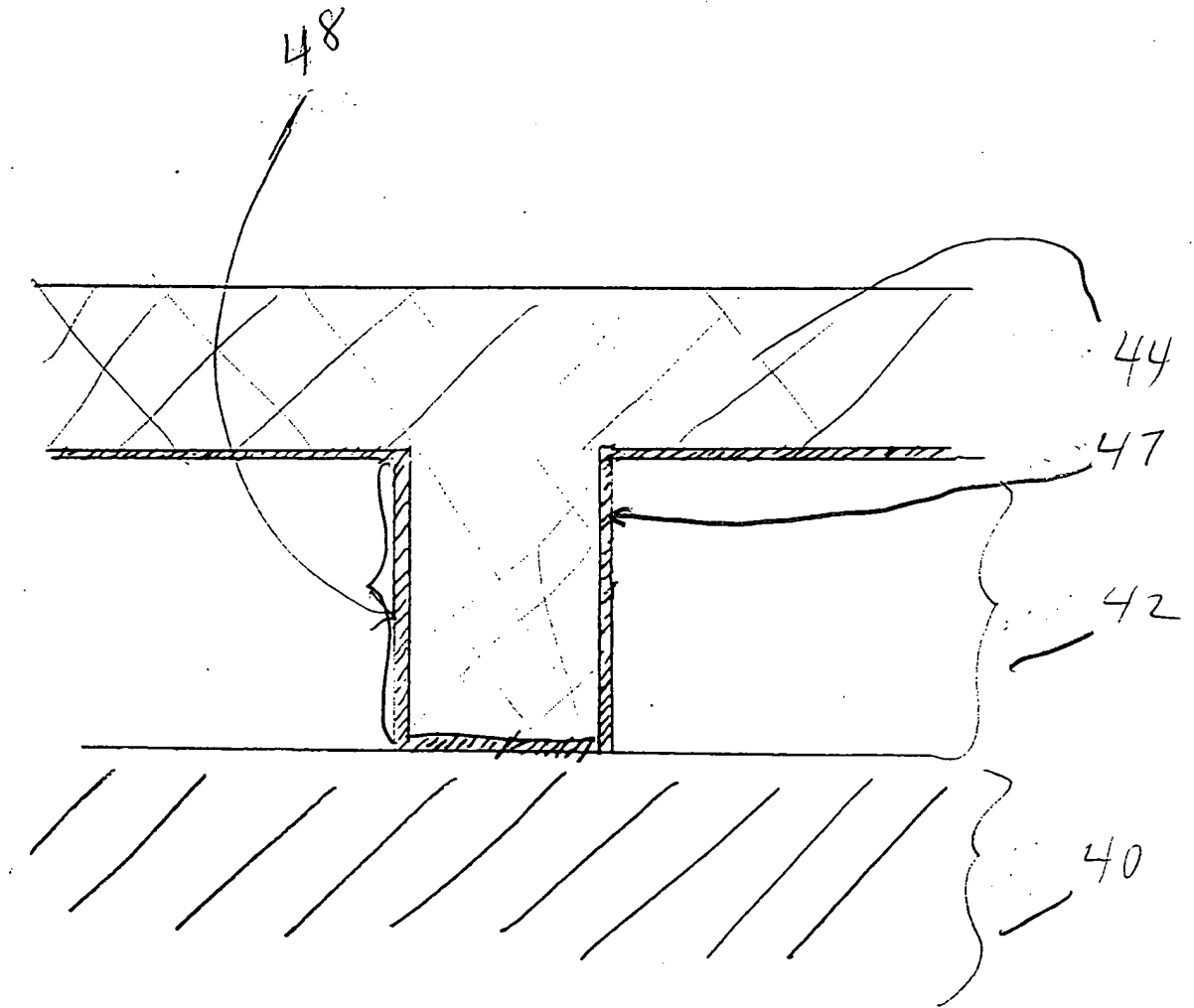


FIG. 3

42390.P7832

007E7 669460

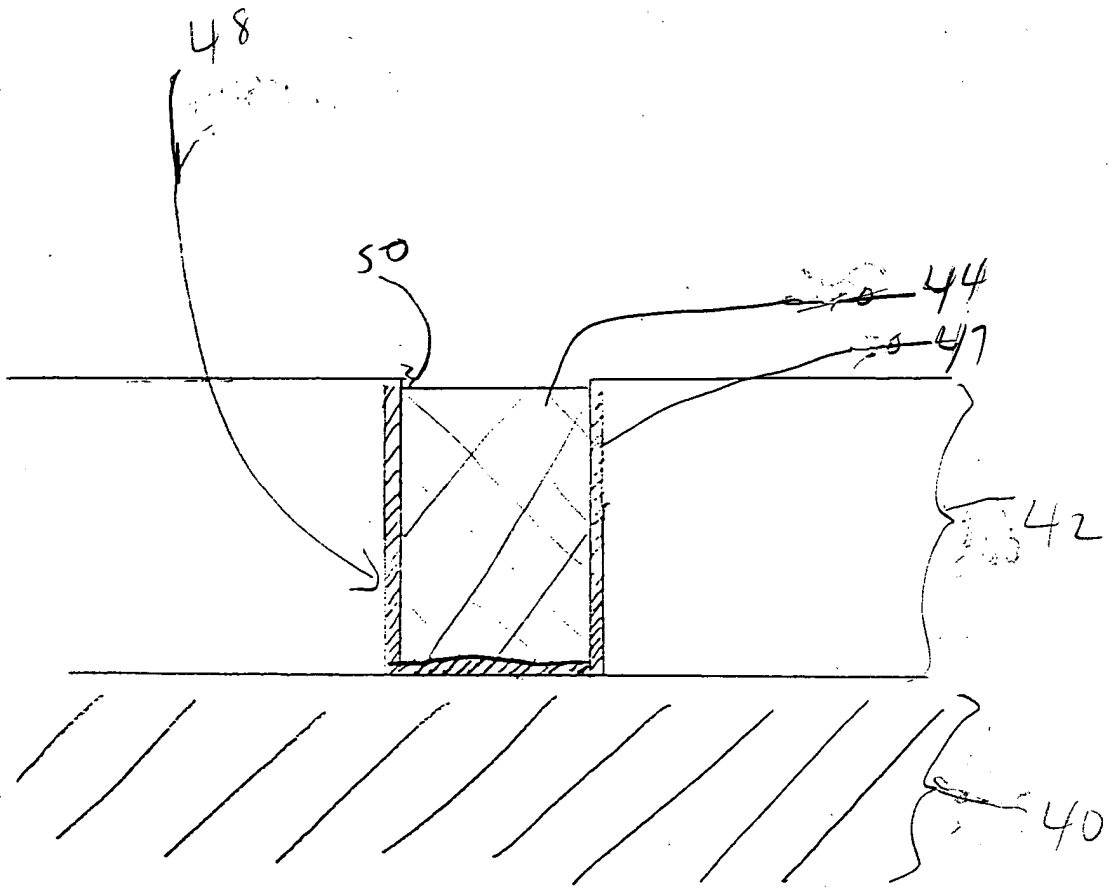


FIG. 4

42390.P7832

004653-1440

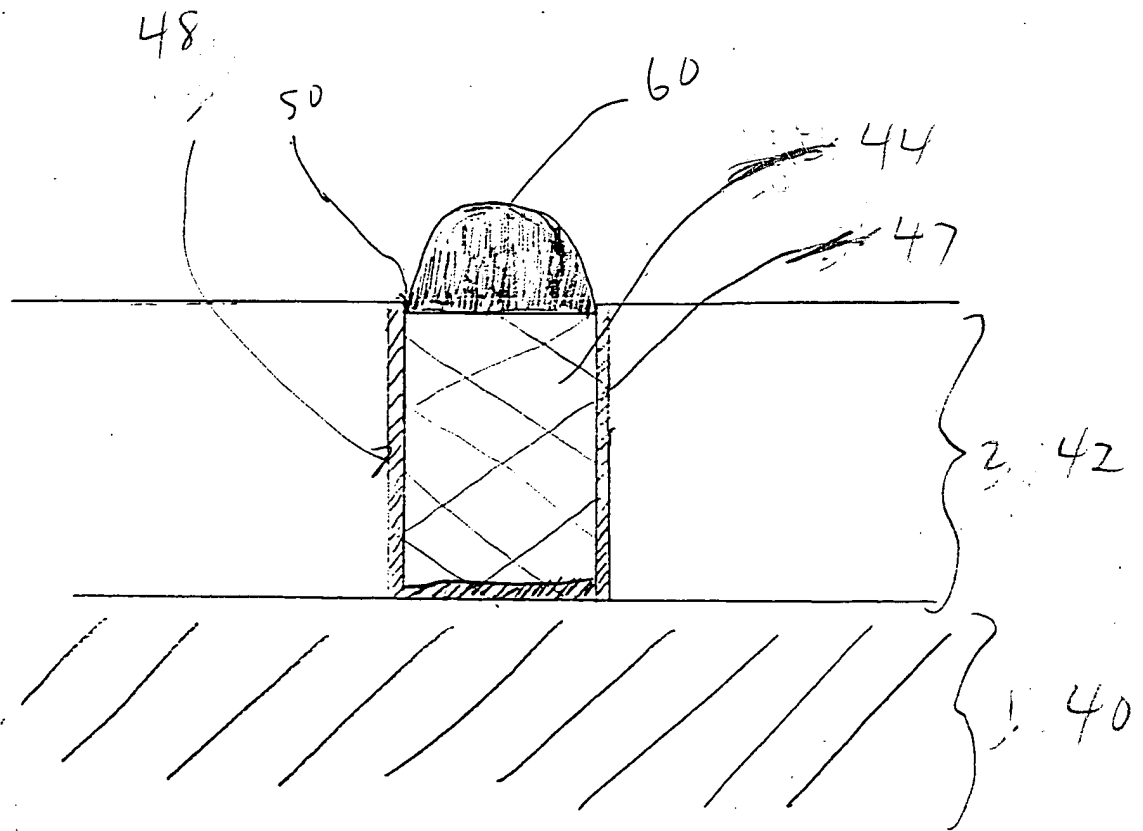


FIG. 5

42390.P7832

62390-2892160

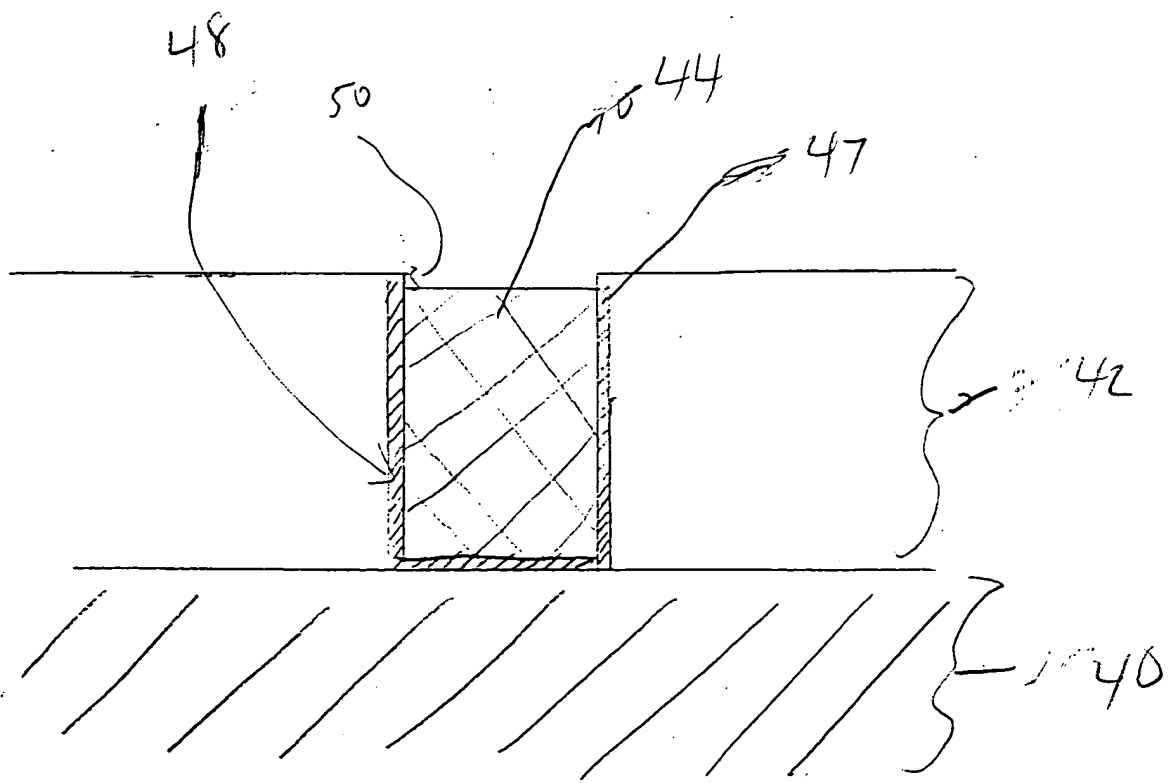


FIG. 6





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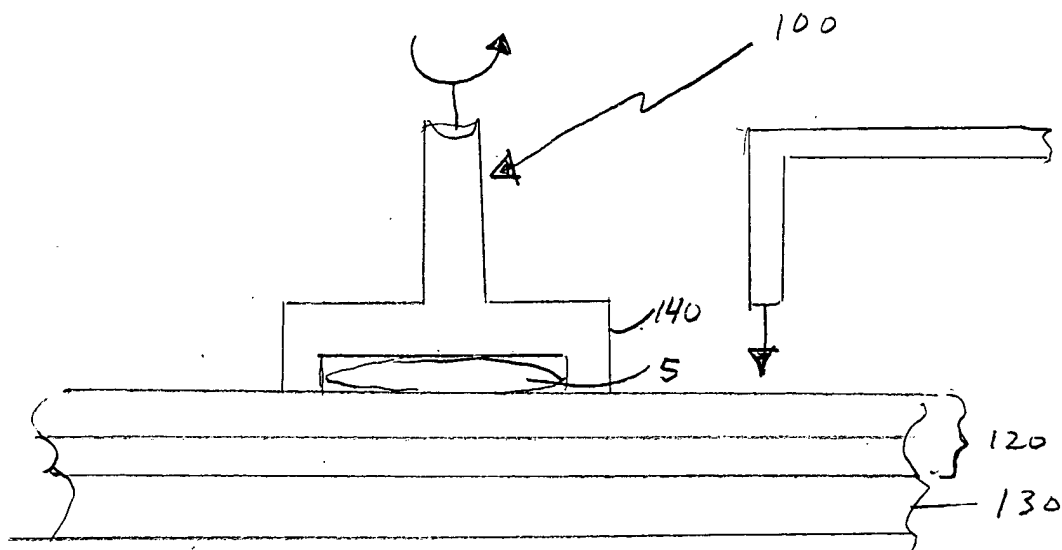


FIG. 8





607667-607668

Vias or contacts are formed in the substrate

200

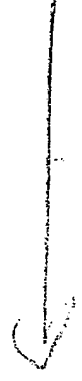


FIG. 91

The substrate having a metal blanket deposited thereon is secured to a polisher 210

A slurry is deposited over the metal layer. 220

The metal layer is polished. 230

A solution comprising hydrogen peroxide and deionized water is deposited over the substrate. 240

metal layer on the

At least one or more particles is removed from the metal layer. 250

FIG. 11